

STN	Skúšobné metódy na elektrotechnické materiály, dosky s plošnými spojmi a iné spájacie štruktúry a zostavy Časť 2-720: Zisťovanie defektov v prepojovacích štruktúrach meraním kapacity	STN EN IEC 61189-2-720 34 6513
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Test methods for electrical materials, circuit boards and other interconnection structures and assemblies - Part 2-720: Detection of defects in interconnection structures by measurement of capacitance

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 06/24

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EUROPEAN STANDARD

EN IEC 61189-2-720

NORME EUROPÉENNE

EUROPÄISCHE NORM

April 2024

ICS 31.180

English Version

Test methods for electrical materials, circuit boards and other
interconnection structures and assemblies - Part 2-720:
Detection of defects in interconnection structures by
measurement of capacitance
(IEC 61189-2-720:2024)

Méthodes d'essai pour les matériaux électriques, les cartes
imprimées et autres structures d'interconnexion et
ensembles - Partie 2-720 : Détection de défauts présents
dans les structures d'interconnexion par mesurage de la
capacité
(IEC 61189-2-720:2024)

Prüfverfahren für elektrische Materialien, Leiterplatten und
andere Verbindungsstrukturen und -Baugruppen - Teil 2-
720: Erkennung von Fehlern in Verbindungsstrukturen
durch Messung der Kapazität
(IEC 61189-2-720:2024)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 61189-2-720:2024 (E)**European foreword**

The text of document 91/1923/FDIS, future edition 1 of IEC 61189-2-720, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61189-2-720:2024.

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Annex ZA (normative)

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<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194-2	-	Printed boards design, manufacture and assembly - Vocabulary - Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies	-	-



IEC 61189-2-720

Edition 1.0 2024-03

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Test methods for electrical materials, circuit boards and other interconnection structures and assemblies –
Part 2-720: Detection of defects in interconnection structures by measurement of capacitance**

**Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles –
Partie 2-720 : Détection de défauts présents dans les structures d'interconnexion par mesurage de la capacité**



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Edition 1.0 2024-03

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Test methods for electrical materials, circuit boards and other interconnection structures and assemblies –
Part 2-720: Detection of defects in interconnection structures by measurement of capacitance**

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Partie 2-720 : Détection de défauts présents dans les structures d'interconnexion par mesurage de la capacité**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**TEST METHODS FOR ELECTRICAL MATERIALS, CIRCUIT BOARDS AND
OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –****Part 2-720: Detection of defects in interconnection
structures by measurement of capacitance**

FOREWORD

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IEC 61189-2-720 has been prepared by IEC technical committee 91: Electronics assembly technology. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1923/FDIS	91/1934/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

A list of all parts in the IEC 61189 series, published under the general title *Test methods for electrical materials, circuit boards and other interconnection structures and assemblies*, can be found on the IEC website.

Future standards in this series will carry the new general title as cited above. Titles of existing standards in this series will be updated at the time of the next edition.

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TEST METHODS FOR ELECTRICAL MATERIALS, CIRCUIT BOARD AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 2-720: Detection of defects in interconnection structures by measurement of capacitance

1 Scope

This part of IEC 61189 provides a method to evaluate specific characteristics of circuit boards by measuring the capacitance between conductor traces and a ground plane and can be used for qualitative comparison of a test specimen to a reference board. This method is not intended for quantitative measurements and for assessment of conformity to a specification.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

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